



Honorary Chairs

Le Hieu Giang, HCM-UTE, Vietnam  
Yu-Lung Lo, NCKU, Taiwan  
Daniel Turner, Sandia, USA

General Co-Chairs

Chau Dinh Thanh, HCM-UTE, Vietnam  
Ming-Tzer Lin, NCHU, Taiwan  
Phillip Reu, Sandia, USA

Program Co-chairs

Vu Van Phong, HCM-UTE, Vietnam  
Truong Nguyen Luan Vu, HCM-UTE, Vietnam  
Do Thanh Trung, HCM-UTE, Vietnam  
Mark Iadicola, NIST, USA

Publicity Co-chairs

Nguyen Van Chung, HCM-UTE, Vietnam  
Motoharu Fujigaki, U-Fukui, Japan  
Dang Quang Vang, HCM-UTE, Vietnam

Local Organizing Committee

Chau Ngoc Thin, HCM-UTE, Vietnam  
Dang Nhat Minh, HCM-UTE, Vietnam  
Dinh Bao Huy, HCM-UTE, Vietnam

International Advisory Board

Akira Kato, Chiba Univ., Japan  
Arikawa Shuichi, Meiji Univ., Japan  
Ayatollahi, Majid Reza, IUST, Iran  
Benoît Blaysat, UCA, France  
Bill Yuh J. Chao, USC, USA  
Changhong Ke, BU, USA  
Chang-Sheng Lin, NKUST, Taiwan  
Chi Hung Hwang, NAIR, Taiwan  
Dang Thien Ngon, HCM-UTE, Vietnam  
Debasis Deb, IITK, India  
Dulal Goldar, DTU, India  
Hui-Min Xie, Tsinghua Univ., China  
Jeong Whan Yoon, KAIST, Korea  
Jian Xiong, HIT, China  
Jin Yang, UT-Austin, USA  
Mai Duc Dai, HCM-UTE, Vietnam  
Ming-Yuan Shen, NCHU, Taiwan  
Pham Son Minh, HCM-UTE, Vietnam  
Qian Kemao, NTU, Singapore  
Qi-Can Zhang, SCU, China  
Ramesh, IITM, India  
Ryan B. Berke, USU, USA  
Satoru Yoneyama, AGU, Japan  
Shyh-Chour Huang, NKUST, Taiwan  
Song-Jeng Huang, NTUST, Taiwan  
Suminar Pratapa, ITS, Indonesia  
Terry Yuan-Fang Chen, NCKU, Taiwan  
Wei-Chung Wang, NTHU, Taiwan  
Yasuyuki Morita, Kumamoto Univ., Japan  
Yi-Lan Kang, TJU, China  
Yum-Ji Chan, NCHU, Taiwan

Conference Sponsors

HCM-UTE  
Correlated Solutions, Inc  
MatchID, Inc.

Venue and Accommodation

Caravelle Saigon Hotel  
19-23 Lam Son Square, Sai Gon Ward, Ho Chi Minh City, Vietnam

Additional Information

Visa applications: <https://evisa.gov.vn>

Contact

E-mail: [icecm-idic2026@hcmute.edu.vn](mailto:icecm-idic2026@hcmute.edu.vn)  
Website: <https://icecm-idic2026.hcmute.edu.vn>  
Hotline: +84 981 479 507 (Vu Van Phong)

Welcome to ICECM/iDICs 2026 Joint Conference, which will be held at Caravelle Saigon Hotel, Ho Chi Minh City, Vietnam, on November 02-05, 2026.

ICECM 2026: International Conference on Experimental and Computational Mechanics 2026

The International Conference on Experimental and Computational Mechanics 2026 (ICECM 2026) is jointly hosted by Ho Chi Minh City University of Technology and Engineering (HCM-UTE), and the Asian Society for Experimental Mechanics (ASEM). The conference aims to provide a high-level international forum for researchers, academics, and practitioners to exchange knowledge and share recent advances, innovative methodologies, and practical applications in the fields of computational and experimental mechanics

iDICs 2026: International Digital Image Correlation Society Annual Meeting 2026

The International Digital Image Correlation Society Annual Meeting 2026 (iDICs 2026) is a leading international forum for researchers, engineers, and practitioners working in the field of digital image correlation (DIC) and full-field optical measurement techniques. The conference is organized by the International Digital Image Correlation Society (iDICs) in collaboration with Ho Chi Minh City University of Technology and Engineering (HCM-UTE). iDICs 2026 aims to provide a platform for presenting cutting-edge research, innovative methodologies, and practical applications of DIC, while fostering knowledge exchange and collaboration among experts from academia, industry, and research institutions worldwide.

The joint conference invites the submission of one-page extended abstracts presenting ongoing research, recent results, or practical applications related to experimental and computational mechanics, digital image correlation, and full-field optical measurement techniques.

We particularly encourage submissions that focus on the following topics (but are not limited to):

- (1) Advanced Mechatronic and Control Systems
- (2) Advanced Mechatronic Systems
- (3) Artificial Intelligence and Advanced Computational Methods in Experimental Mechanics
- (4) Artificial Intelligence and Machine Learning in Mechatronics
- (5) DIC Algorithms and Computational Methods
- (6) DIC and other Optical Techniques in Experimental Mechanics
- (7) DIC for Advanced Manufacturing Monitoring
- (8) DIC in Materials Testing and Constitutive Model Calibration
- (9) DIC Standardization and Uncertainty Quantification
- (10) Digital Volume Correlation
- (11) Experimental and Computational Fluid Mechanics
- (12) Experimental and Computational Mechanics for Dynamic Response and Extreme Environmental Conditions
- (13) Experimental and Computational Mechanics for Manufacturing and Material Behavior Analysis
- (14) Experimental and Computational Mechanics for Material Characterization and Structural Mechanics Analysis
- (15) Experimental and Computational Mechanics for Semiconductor Technology
- (16) Experimental and Computational Mechanics in Biomechanics Application
- (17) Experimental and Computational Multiscale Methodologies
- (18) Global and Adaptive DIC Methods
- (19) High-speed DIC and Modal Analysis
- (20) Mechatronics and Control System
- (21) Microscale Measurements with DIC
- (22) Modern and Sustainable Industrial Engineering and Management
- (23) Novel Imaging Modalities

Paper submission

All submissions must be in English. The one-page extended abstracts are to be submitted electronically in PDF format via the CMT submission link: <https://cmt3.research.microsoft.com/ICECMiDICs2026>.

Important dates

|                                         |                                                                    |
|-----------------------------------------|--------------------------------------------------------------------|
| Proposal for special session            | April 30, 2026                                                     |
| Special session acceptance notification | May 07, 2026                                                       |
| Abstract submission deadline            | <del>June 20, 2026</del> extended to August <del>45</del> 29, 2026 |
| Abstract acceptance notification        | <del>June 30, 2026</del> extended to August 31, 2026               |
| Early-bird registration & payment ends  | <del>July 31, 2026</del> extended to September 10, 2026            |
| Registration & payment deadline         | <del>August 30, 2026</del> extended to September 15, 2026          |
| Letter of invitation delivery           | October 01, 2026                                                   |

Training courses (November 02, 2026)

The iDICs will offer several of its most popular training courses at Ho Chi Minh City University of Technology and Engineering (HCM-UTE) before ICECM/iDICs 2026 Joint Conference:

- DIC101** – Learn the Good Practices Guide (GPG) and prepare for Level 1 Certification (full day).
- How to Pattern...Everything** – Learn how to pattern for DIC at multiple scales (½ day).
- Measurement Uncertainty** – Learn the approved methods of assessing the accuracy of your DIC measurement (½ day).

Registration fees

| Category                                                                                                      | Early-bird rate<br>(by Sept. 10, 2026) | Standard rate<br>(from Sept. 11, 2026) |
|---------------------------------------------------------------------------------------------------------------|----------------------------------------|----------------------------------------|
| Regular author registration                                                                                   | 500 USD                                | 600 USD                                |
| Student author registration<br>[Note]: The student must be the first author and the presenter of the abstract | 250 USD                                | 300 USD                                |
| General registration                                                                                          | 500 USD                                | 600 USD                                |
| General student registration                                                                                  | 250 USD                                | 300 USD                                |
| Training course registration                                                                                  | 100 USD                                | 100 USD                                |

Sponsorship opportunities

ICECM/iDICs 2026 sponsorships at the Bronze through Gold level will include acknowledgement in the printed conference program, during various sessions, and the listed items offered at the different sponsorship levels. For more details, please visit [HERE](#).

